





## Features & Benefits

- The IceLED modular active LED coolers are specifically designed for luminaires using the Seoul Semiconductor LED COB. Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
- For spot and downlight designs from 2,000 to 10,000 lumen
- Thermal resistance range Rth 0.46 0.58°C/W
- Modular design with mounting holes foreseen for Seoul Semiconductor ZC 25, ZC 40 COB LED Arrays, direct mounting or with Zhaga Book 3 LED holder.
- Diameter 99mm Standard height 45mm & 55mm Other heights on request
- Anti-vibration low-noise fan <21dB@1m</li>
- High lifetime design >60Khrs (L 10 life time @40°C)
- Warranty 5 years



## **Order Information**





**SEOUL SEMICONDUCTOR** 

**Example: IceLED 450** 

IceLED 1

1 Height (mm)

Overall height top to bottom

(Fan height 25mm)

IceLED 450 - 45mm

IceLED 550 - 55mm

Ice LED is designed in this way

that you can mount various LED modules on the same LED cooler

Simple mounting with self tapping screws

Recommened screw force 6lb/in

Screws are avaliable from MechaTronix









## **Product Details**



 $<sup>^{</sup>st 1}$  3D files are avaliable in ParaSolid, STP and IGS on request

Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module To calculate the dissipated power please use the following formula:  $Pd = Pe \times (1-\eta L)$ 

Pd - Dissipated power

Pe - Electrical power

 $\eta L$  = Light effciency of the LED module

#### **Notes:**

- MechaTronix reserves the right to change products or specifications without prior notice.
- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MechaTronix.



<sup>\*2</sup> The fan requires a constant voltage power source of 12Vdc, 50mA

 $<sup>^{*3}</sup>$  The thermal resistance Rth is determined with a calibrated heat source of 30mm x 30mm central placed on the heat sink, Tamb 40 $^{\circ}$ and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

 $<sup>^{*4}</sup>$  Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb  $\sf 50^\circ C$ The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed







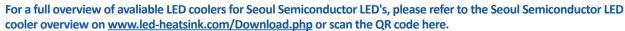
## **Mounting Options**

The IceLED modular active LED coolers are standard foreseen from a variety of mounting holes which allow direct mounting of LED engines, COB's and secondary optics on the LED heat sink.

In this way mechanical afterwork and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED coolers.

Below you find an overview of Seoul Semiconductor LED COB's which standard fit on the IceLED LED cooler.

MechaTronix performs thermal validation tests on each of the LED modules mounted on the LED cooler and publishes this data in the LED brand thermal validation reports.





#### Seoul Semiconductor LED COB

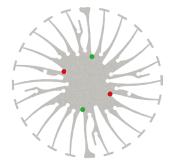


#### **SEOUL SEMICONDUCTOR**

The new Seoul Semiconductor ZC series Chip-On-Board (COB) LED Arrays offer high lumen density and efficacies of up to 140lm/W in a single, easy-to-use LED component family. Available in all major color temperatures from 2700K up to 6000K, these high flux packages deliver system level performance of 700 lumens to over 6,000 lumens. The new ZC series family is available in a single 3-step MacAdam Ellipse binning, ensuring excellent color consistency with minimum CRI options of 70, and 80 combining high quality of light with high efficacy.

#### Mounting indicator marks overview

MechaTronix recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended. Thermal pads or phase change thermal pads can be preapplied from MechaTronix.







## Seoul Semiconductor ZC 25 / 40 LED COB

### **Model names**

- SDW04F1C
- SDW84F1C
- SDW94F1C
- SDW05F1C
- SDW85F1C • SDW95F1C

# **Mounting**

- Direct mounting with 2 self tapping screws M3 x 6mm **Red indicator marks**
- With Zhaga Book 3 LED holder BJB spotlight connector 47.319.2030 Mounting with 2 self tapping screws M3 x 8mm **Green indicator marks**

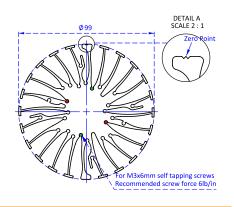


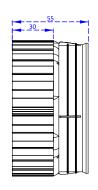






# **Drawings & Dimensions**



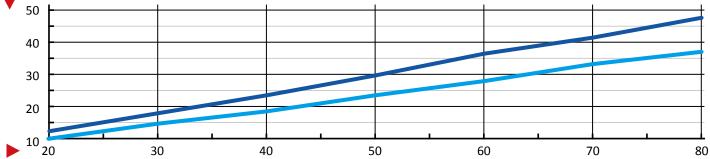




# **Thermal Data**

Pd = Pe x (1-ηL)			LED Light efficiency, ηL (%)			Heat sink to ambient thermal resistance R <sub>hs-amb</sub> (°C/W)		Heat sink to ambient temperature rise T <sub>hs-amb</sub> (°C)	
			17%	20%	25%	IceLED 450	IceLED 550	IceLED 450	IceLED 550
Dissipated Power Pd(W)	20	Electrical Power Pe(W)	24.1	25.0	26.7	0.62	0.50	12	10
	25		30.1	31.3	33.3	0.62	0.49	15	12
	30		36.1	37.5	40.0	0.61	0.49	18	15
	35		42.2	43.8	46.7	0.61	0.49	21	17
	40		48.2	50.0	53.3	0.60	0.48	24	19
	50		60.2	62.5	66.7	0.60	0.48	30	24
	60		72.3	75.0	80.0	0.59	0.47	36	28
	70		84.3	87.5	93.3	0.59	0.47	41	33
	80		96.4	100.0	106.7	0.59	0.47	47	37





Dissipated Power Pd(W)

